



*National Semiconductor*

Dear Valued Customer,

The current mechanical specifications for the package can be found at the [www.national.com](http://www.national.com) web site or by clicking the following link:

<http://www.national.com/packaging/folders/sda14b.html>

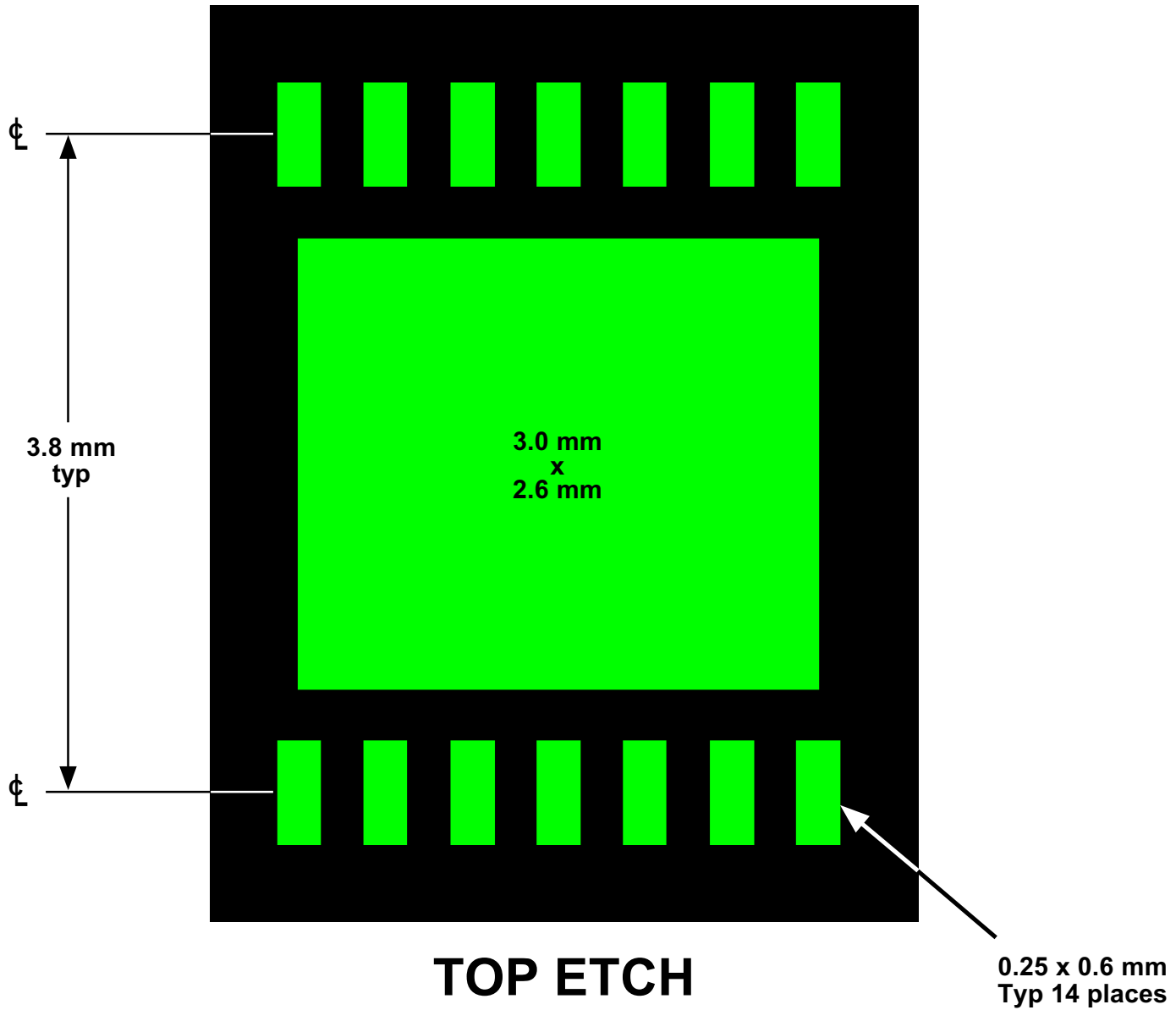
The following pages illustrate the recommended package footprints that apply to this package configuration. They are included in GERBER format for easy incorporation into most PCB layout packages.

For technical support, contact:

<http://www.national.com/support/>

Sincerely yours,

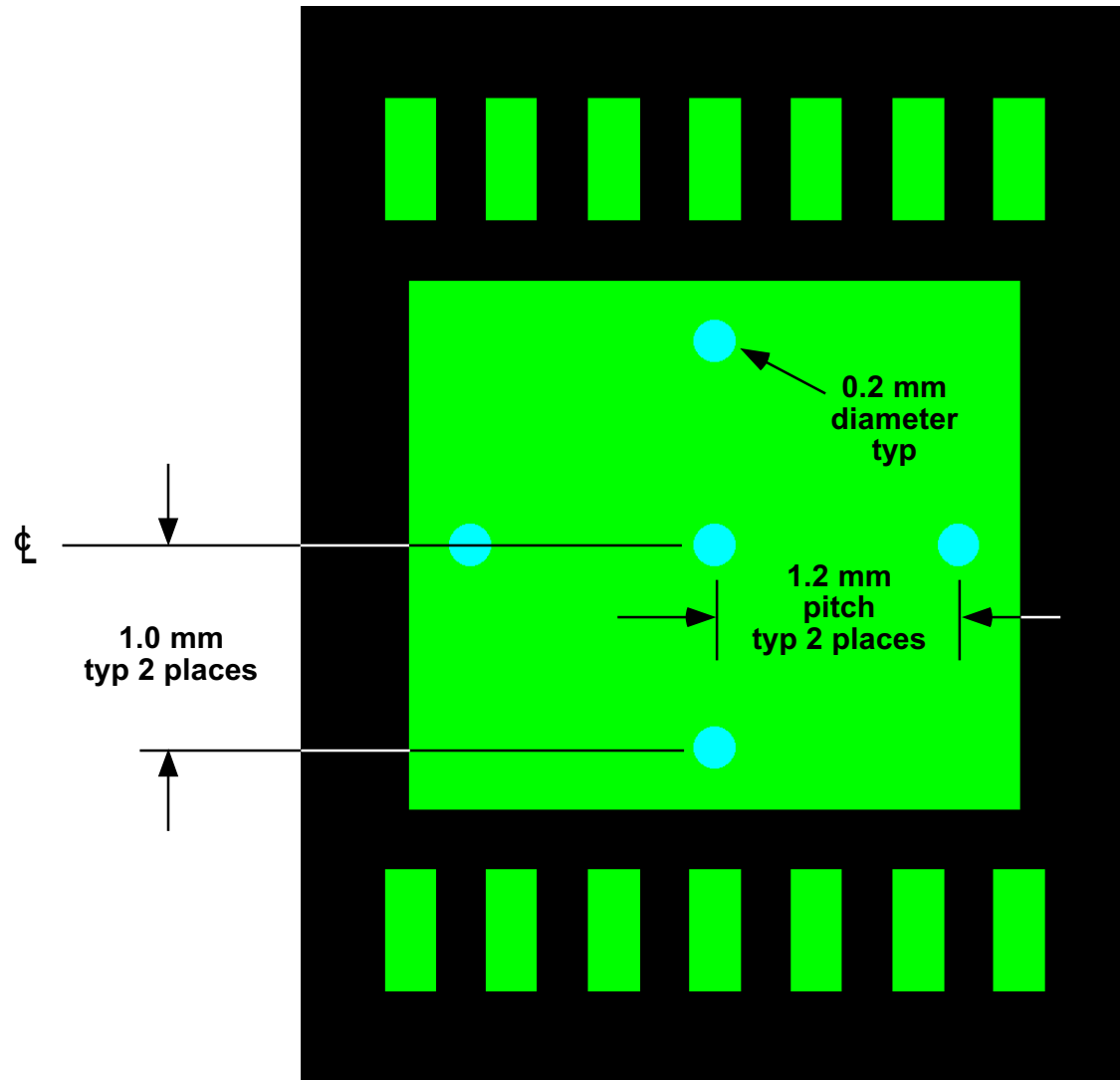
National Semiconductor




## TOP ETCH

 = Exposed FR4     = Exposed metal


**NOTE:**  
Refer to package mechanical drawing at the website for complete mechanical dimensions.

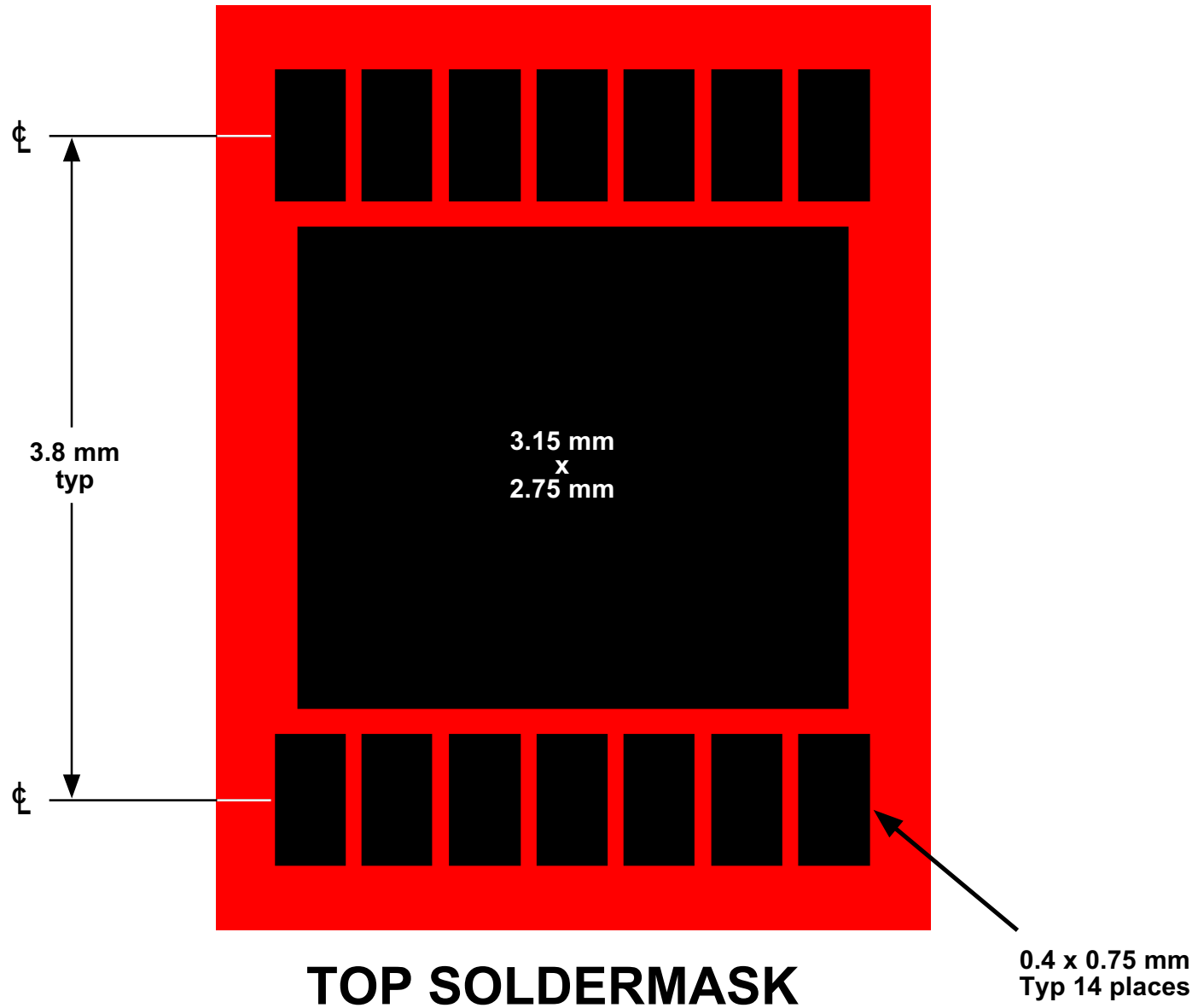


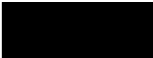
## TOP ETCH with THERMAL VIAS

 = Exposed FR4

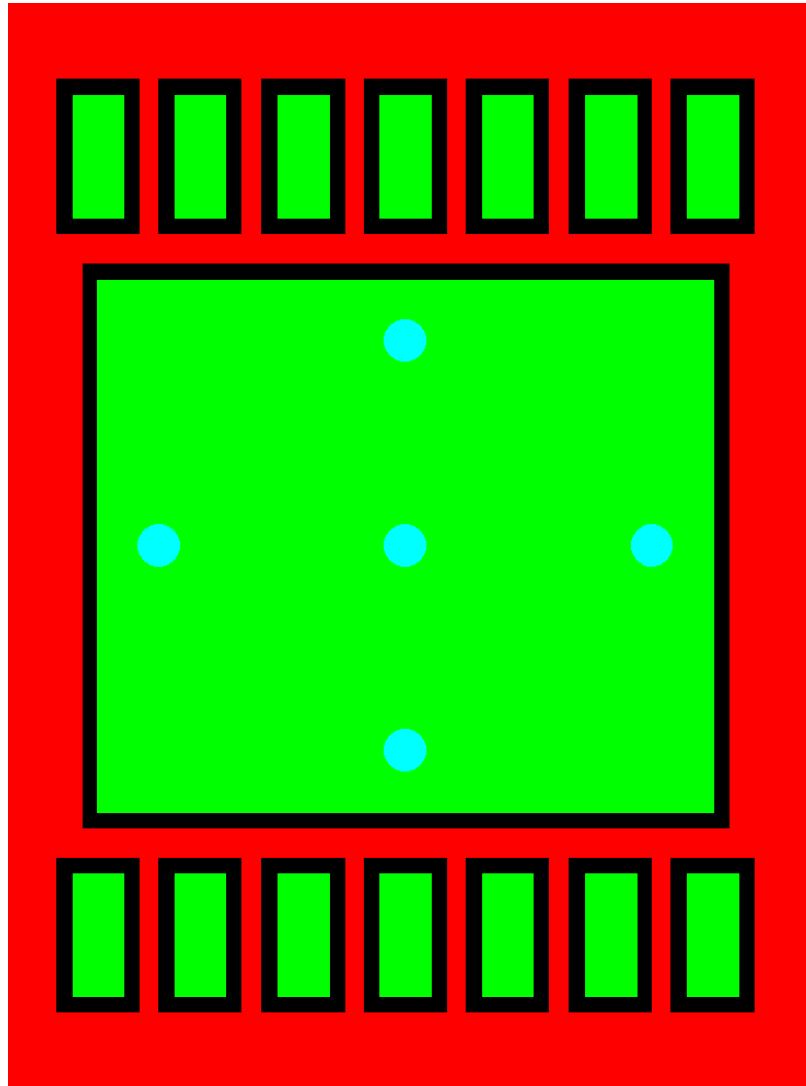
 = Exposed metal

 = Thermal Vias




 = Exposed FR4


 = Mask over FR4



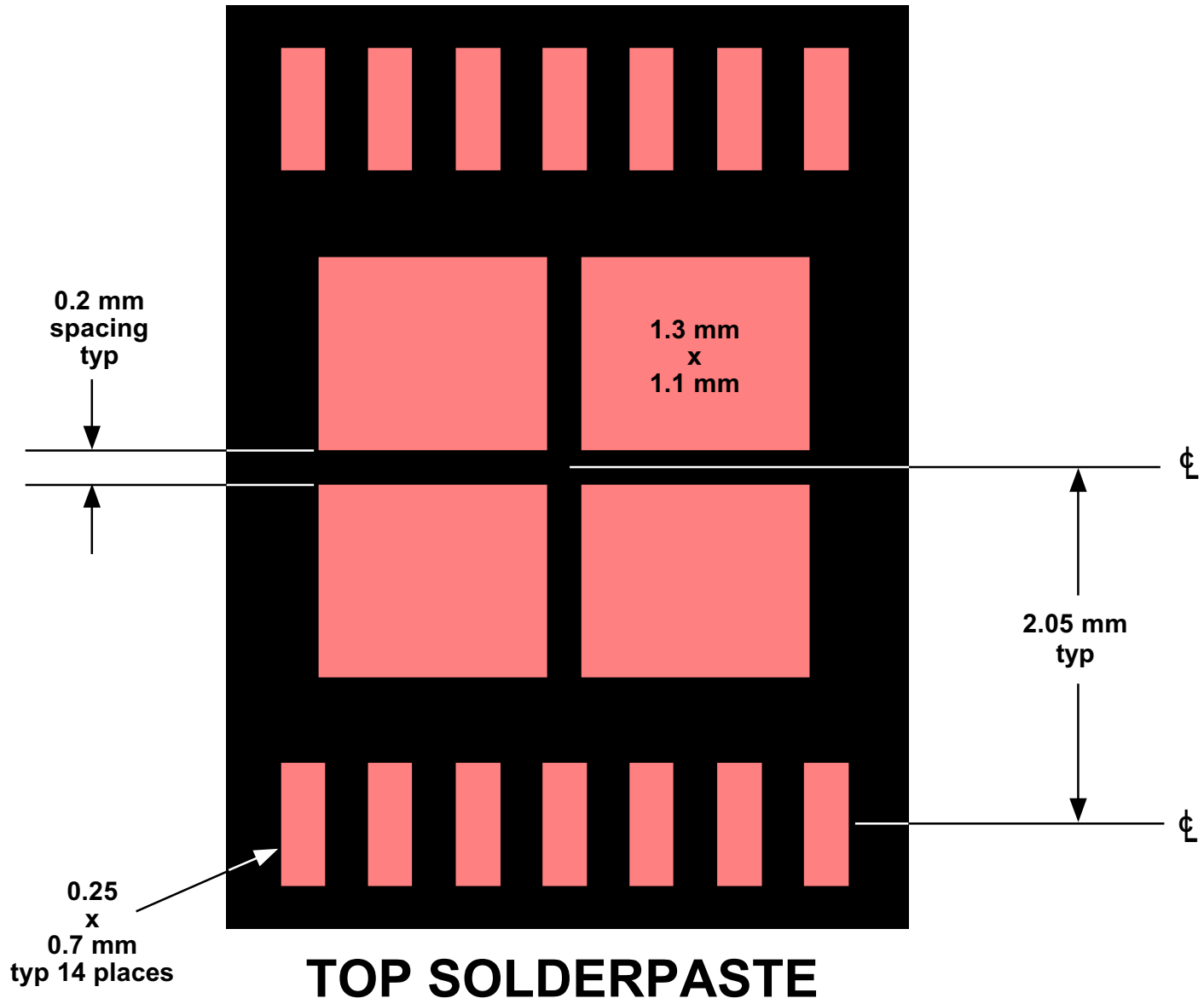
## TOP ETCH + SOLDERMASK + VIAS

 = Exposed FR4

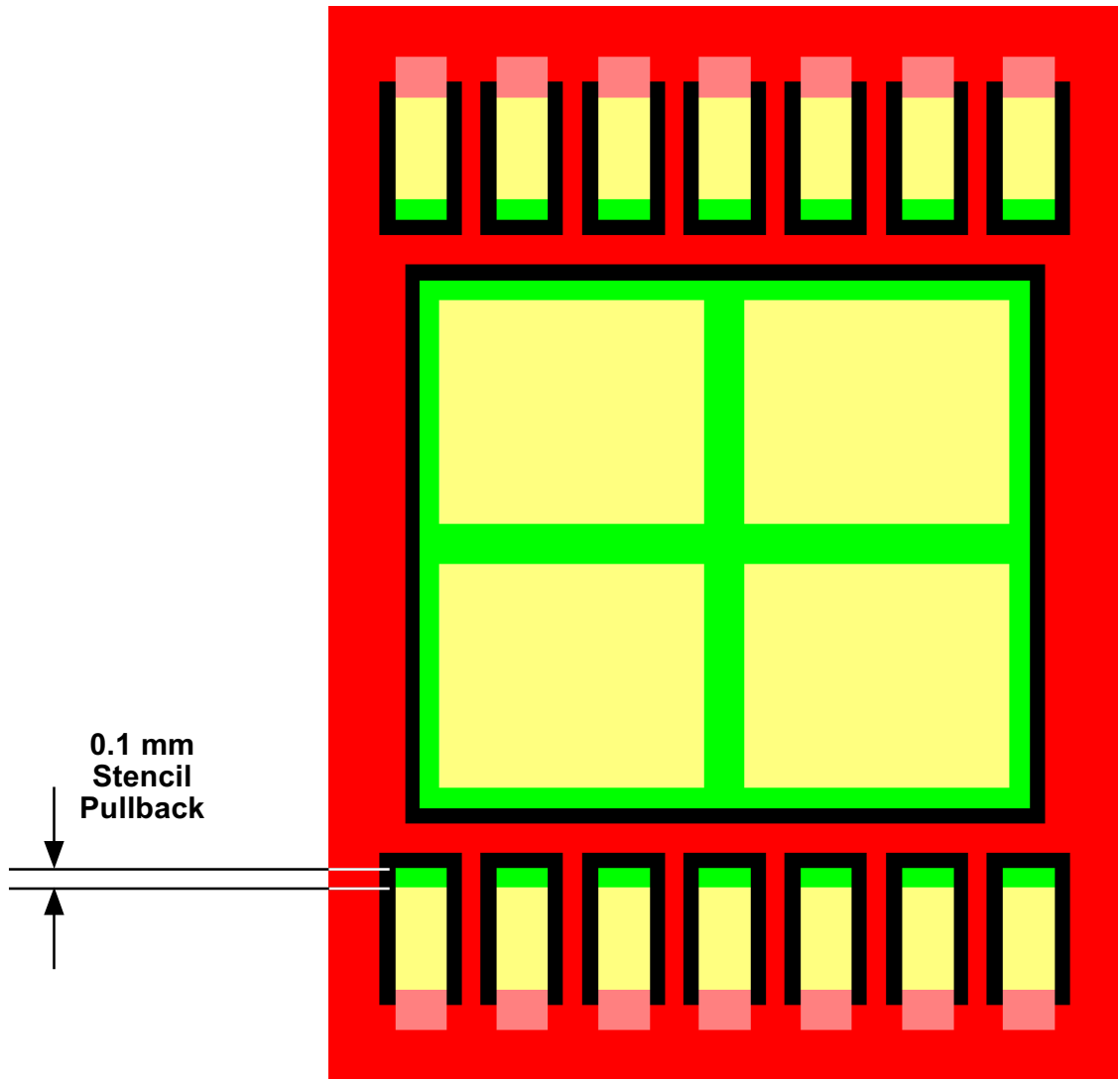
 = Exposed metal

 = Thermal Vias

 = Mask over FR4

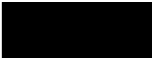



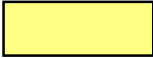


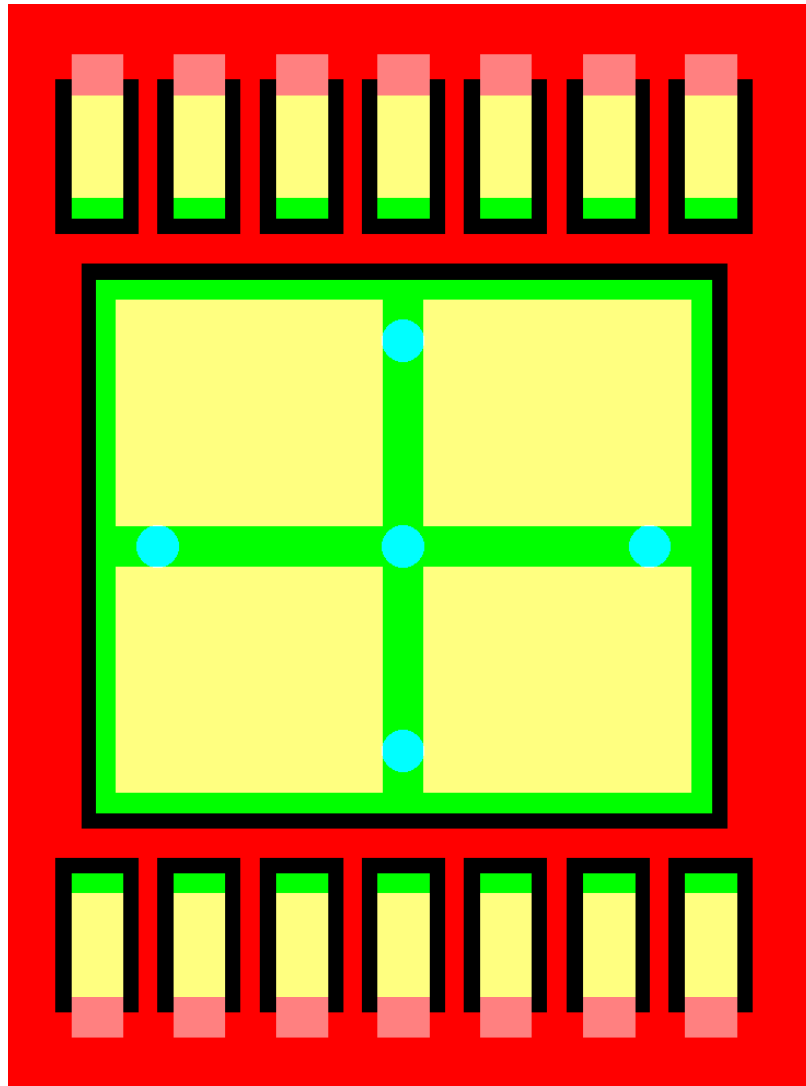
 = Paste



0.1 mm  
Stencil  
Pullback

## TOP ETCH + SOLDERMASK + SOLDERPASTE

- |   |                 |   |                       |   |                                    |
|---|-----------------|---|-----------------------|---|------------------------------------|
|  | = Exposed FR4   |    | = Exposed metal       |  | = Paste over FR4<br>(0.2mm offset) |
|  | = Mask over FR4 |  | = Paste over<br>Metal |   |                                    |



## TOP ETCH + MASK + SOLDERPASTE with VIAS

